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Tomoo IKEDA *et al.*
Attorney Docket No. 01165.0963

**ANNEXES TO THE
PRELIMINARY EXAMINATION REPORT
(ARTICLE 34 AMENDMENTS)**

**Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

Sir:

REQUEST FOR SUBSTITUTION OF REPLACEMENT SHEETS

Please substitute the attached replacement pages 59-62 of the translation of the claims of the Article 34 amendments for pages 59-64 of the claims in the enclosed translation of the as-filed PCT Application. It is respectfully requested that the claims on replacement pages 59-63 be examined during examination of the patent application. Claims 1-4, 7, 10, 11 14, 17-21, 24-26, 29, 30, 33 and 36-38 are currently pending.

Respectfully submitted,

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Dated: September 19, 2006

By: 

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EFC/FPD/sem

What is claimed is:

1. (Amended) An oscillator device comprising:
 - an oscillator having a vibrating prong and
 - a base portion with a first reference portion;
 - 5 a package;
 - a mounting base with a second reference
 - portion provided inside said package; and
 - a bonding material for fixing said
 - oscillator to said mounting base by aligning said first
 - 10 reference portion with said second reference portion by
 - utilizing a self-alignment effect occurring due to
 - surface tension,
 - wherein said second reference portion is
 - formed by inclining at a certain angle with respect to a
 - 15 center line of said package.
2. The oscillator device according to claim 1,
wherein said first reference portion has three straight
line portions defining an outer shape of said base
portion, and said second reference portion has three
20 straight line portions corresponding in position to said
three straight line portions that constitute said first
reference portion.
3. The oscillator device according to claim 2,
wherein one of said three straight line portions
25 constituting said second reference portion is a contact
line between an inside wall of said package and said
mounting base.
4. The oscillator device according to claim 1,
wherein said first reference portion has two side wall
30 faces defining an outer shape of said oscillator, and
said second reference portion has two bonding faces
corresponding to said two side wall faces.
5. (Deleted)
6. (Deleted)
- 35 7. The oscillator device according to claim 1,
wherein said first reference portion has three straight
line portions defining an outer shape of said oscillator,

said second reference portion has two straight line portions corresponding in position to at least two of said straight line portions constituting said first reference portion, and an inside wall of said package has a bonding face corresponding to at least one of said straight line portions constituting said first reference portion.

8. (Deleted)

9. (Deleted)

10. The oscillator device according to claim 7, wherein width (W) of said base portion and width (Wd) of said mounting base satisfy the relation $0.86W < Wd < 1.16W$.

11. (Amended) The oscillator device according to claim 10, wherein the width of said base portion is substantially equal to the width of said mounting base.

12. (Deleted)

13. (Deleted)

14. The oscillator device according to claim 7, wherein said package is a ceramic package.

15. (Deleted)

16. (Deleted)

17. The oscillator device according to claim 1, wherein said oscillator is a crystal plate.

18. (Amended) A method for manufacturing an oscillator device, comprising the steps of:

forming an oscillator having a vibrating prong and a base portion with a first reference portion;

forming a package having a mounting base with a second reference portion which is formed by inclining at a certain angle with respect to a center line of said package;

placing said oscillator on said mounting base by aligning said first reference portion with said second reference portion by utilizing a self-alignment effect occurring due to surface tension of a bonding material; and

hardening said bonding material.

19. The method for manufacturing an oscillator device according to claim 18, wherein said first reference portion is formed so as to have three straight line portions defining an outer shape of said base portion, and

said second reference portion is formed so as to have three straight line portions corresponding in position to said three straight line portions that constitute said first reference portion.

20. The method for manufacturing an oscillator device according to claim 19, wherein one of said three straight line portions constituting said second reference portion is a contact line between an inside wall of said package and said mounting base.

21. The method for manufacturing an oscillator device according to claim 18, wherein said first reference portion is formed so as to have two side wall faces defining an outer shape of said oscillator, and said second reference portion is formed so as to have two bonding faces corresponding to said two side wall faces.

22. (Deleted)

23. (Deleted)

24. The method for manufacturing an oscillator device according to claim 18, wherein said oscillator is formed by etching.

25. The method for manufacturing an oscillator device according to claim 18, wherein said mounting base is formed integrally with said package.

26. The method for manufacturing an oscillator device according to claim 18, wherein said first reference portion is formed so as to have three straight line portions defining an outer shape of said crystal plate, and

said second reference portion is formed so as to have two straight line portions corresponding in

position to at least two of said straight line portions constituting said first reference portion, while an inside wall of said package is formed so as to have a bonding face corresponding to at least one of said
5 straight line portions constituting said first reference portion.

27. (Deleted)

28. (Deleted)

29. The method for manufacturing an oscillator
10 device according to claim 26, wherein width (w) of said base portion and width (wd) of said mounting base satisfy the relation $0.86W < Wd < 1.16W$.

30. The method for manufacturing an oscillator
15 device according to claim 29, wherein said base portion is formed so as to have a width substantially equal to the width of said mounting base.

31. (Deleted)

32. (Deleted)

33. The method for manufacturing an oscillator
20 device according to claim 26, wherein said package is a ceramic package.

34. (Deleted)

35. (Deleted)

36. The method for manufacturing an oscillator
25 device according to claim 18, wherein said oscillator is a crystal plate.

37. (Added) The oscillator device according to
claim 1, wherein said certain angle is an angle such that, when said oscillator device is mounted in an
30 apparatus, a longitudinal direction of said vibrating prong is parallel to a predefined spinning axis of said oscillator device.

38. (Added) The method for manufacturing an
oscillator device according to claim 18, wherein said
35 certain angle is an angle such that, when said oscillator device is mounted in an apparatus, a longitudinal direction of said vibrating prong is parallel to a

predefined spinning axis of said oscillator device.